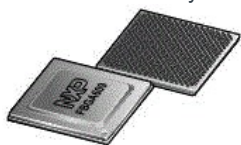


# SIMX8DX5AVLF1BB(Active)

Package FBGA609, fine-pitch ball grid array package; 609 terminals, 0.8 mm pitch, 21 mm x 21 mm x 2.37 mm body



[Buy Options](#) | 
 [Operating Characteristics](#) | 
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 [Quality Information](#) | 
 [Shipping Information](#)

## Buy Options

SIMX8DX5AVLF1BB  
 935389375557  
 Active  
 TRAY-Tray, Bakeable, Multiple in Drypack

Min. Package Quantity: 60

Lead Time: 20 weeks

>

Available Distributors: SIMX8DX5AVLF1BB



SIMX8DX5AVLF1BBR  
 935389375518  
 Active  
 REEL-Reel 13" Q1/T1 in Drypack

Min. Package Quantity: 500

Lead Time: 20 weeks

## Operating Characteristics

No information available

## Environmental Information

Material Declaration	Pb-Free	EU RoHS	Halogen Free	RHF Indicator	REACH SVHC	Weight (mg)
SIMX8DX5AVLF1BB( 935389375557)	Yes	Yes	Yes	D	<a href="#">REACH SVHC</a>	3081.5
<a href="#">SIMX8DX5AVLF1BBR( 935389375518)</a>	Yes	Yes <a href="#">Certificate Of Analysis (CoA)</a>	Yes	D	<a href="#">REACH SVHC</a>	3081.5

## Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
SIMX8DX5AVLF1BB ( 935389375557)	No	3	260	40
<a href="#">SIMX8DX5AVLF1BBR ( 935389375518)</a>	No	3	260	40

## Shipping Information

Part Number	Harmonized Tariff (US) <a href="#">Disclaimer</a>	Export Control Classification Number (US)
SIMX8DX5AVLF1BB ( 935389375557)	854231	5A992C
<a href="#">SIMX8DX5AVLF1BBR</a> ( 935389375518)	854231	5A992C

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